## Am2148/Am2149 Am21L48/Am21L49

1024x4 Static RAM

#### DISTINCTIVE CHARACTERISTICS

- High speed access times as fast as 35 ns
- Fully static storage and interface circuitry
- Automatic power-down when deselected (Am2148)
- TTL-compatible interface levels

- · Low power dissipation
  - Am2148: 990 mW active, 165 mW power down
- Am21L48: 688 mW active, 110 mW power down
   High output drive
- Up to seven standard TTL loads

#### **GENERAL DESCRIPTION**

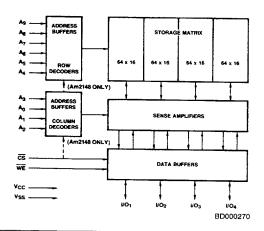
The Am2148 and Am2149 are high-performance, static, N-Channel, read/write, random-access memories, organized as 1024 x 4. Operation is from a single 5-V supply, and all input/output levels are identical to standard TTL specifications. The Am2148 and Am2149 are the same except that the Am2148 offers an automatic  $\overline{CS}$  power-down feature.

The Am2148 remains in a low-power standby mode as long as  $\overline{\text{CS}}$  remains HIGH, thus reducing its power requirements.

The Am2148 power decreases from 990 mW to 165 mW in the standby mode. The  $\overline{\text{CS}}$  input does not affect the power dissipation of the Am2149.

Data readout is not destructive and has the same polarity as data input.  $\overline{\text{CS}}$  provides for easy selection of an individual package when the outputs are OR-tied.

#### **BLOCK DIAGRAM**



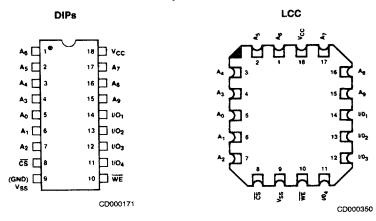
#### PRODUCT SELECTOR GUIDE

Part Number  Maximum Access Time (ns)		Am2148/9 A -35	Am2148/9 -45	Am21L48/9 -45	Am2148/9 -55	Am21L48/9 -55	Am2148/9 -70	Am21L48/9
			45	45	55	55	70	70
Icc Max. (mA)	0 to	180	180	125	180	125	180	125
I <sub>SB</sub> * Max. (mA)	+70°C	30	30	20	30	20	30	20
I <sub>CC</sub> Max. (mA)	-55 to	N/A	180	N/A	180	N/A	180	N/A
I <sub>SB</sub> * Max. (mA)	+ 125°C	+ 125°C N/A	30	N/A	30	N/A	30	N/A

<sup>\*</sup>Am2148 and Am21L48 only.

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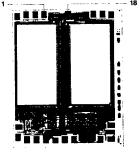
#### CONNECTION DIAGRAMS Top View



Note: Pin 1 is marked for orientation.

#### METALLIZATION AND PAD LAYOUT

Address D	esignators				
External	Internal				
A <sub>0</sub>	A <sub>7</sub>				
A <sub>1</sub>	A <sub>8</sub>				
A <sub>2</sub>	Ag A6				
А3					
A4	A <sub>5</sub>				
A <sub>5</sub>	A4				
A <sub>6</sub>	A <sub>3</sub>				
A <sub>7</sub>	A <sub>2</sub>				
A <sub>8</sub>	A <sub>1</sub>				
Ag	Ao				



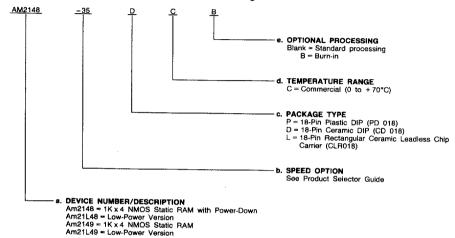
Die Size: 0.107" x 0.145"

#### ORDERING INFORMATION

#### Standard Products

AMD standard products are available in several packages and operating ranges. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option (if applicable)
- c. Package Type
- d. Temperature Range
- e. Optional Processing



Valid	Combinations
AM2148-35	
AM2149-35	$\neg$
AM21L48-45	7
AM21L49-45	PC, PCB,
AM21L48-55	DC, DCB, LC, LCB
AM21L49-55	7
AM21L48-70	$\neg$
AM21L49-70	7
AM2148-45	
AM2149-45	7
AM2148-55	PC, PCB,
AM2149-55	DC, DCB, LC, LCB
AM2148-70	7 25, 255
AM2149-70	$\neg$

#### Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult MSIS sales department to confirm availability of specific valid combinations, and to obtain additional data on MSIS's standard military grade products.

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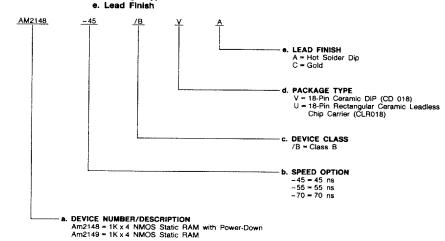
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Am2148/Am2149/Am21L48/Am21L49

## MILITARY ORDERING INFORMATION APL Products

AMD products for Aerospace and Defense applications are available in several packages and operating ranges. APL (Approved Products List) products are fully compliant with MIL-STD-883C requirements. The order number (Valid Combination) is formed by a combination of: a. Device Number

- b. Speed Option (if applicable)
- c. Device Class
- d. Package Type



Valid Co	mbinations
AM2148-45	
AM2149-45	
AM2148-55	/BVA
AM2149-55	/BVA
AM2148-70	
AM2149-70	
AM2148-45	
AM2149-45	
AM2148-55	(5).10
AM2149-55	/BUC
AM2148-70	
AM2149-70	7

#### Valid Combinations

Valid Combinations list configurations planned to be supported in volume for this device. Consult MSIS sales department to confirm availability of specific valid combinations, and to obtain additional data on MSIS's standard military grade products.

#### Group A Tests

Group A Tests consist of Subgroups 1, 2, 3, 7, 8, 9, 10, 11.

#### PIN DESCRIPTION

#### A<sub>0</sub> - A<sub>9</sub> Address Inputs

The address input lines select the RAM location to be read or written.

#### CS Chip Select (Input, Active LOW)

The Chip Select selects the memory device.

#### WE Write Enable (Input, Active LOW)

When  $\overline{\text{WE}}$  is LOW and  $\overline{\text{CS}}$  is also LOW, data is written into the location specified on the address pins.

### I/O<sub>1</sub>-I/O<sub>4</sub> Data In/Out Bus (Bidirectional, Active HIGH)

These I/O lines provide the path for data to be read from or written to the selected memory location.

V<sub>CC</sub> Power Supply

VSS Ground

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#### ABSOLUTE MAXIMUM RATINGS

Storage Temperature65 to	+ 150°C
Ambient Temperature with	
Power Applied55 to	+ 125°C
Supply Voltage0.5 V to	+7.0 V
Signal Voltages with	
Respect to Ground3.5 V to	+7.0 V
Power Dissipation	1.2 W
DC Output Current	20 mA

Stresses above those listed under ABSOLUTE MAXIMUM RATINGS may cause permanent device failure. Functionality at or above these limits is not implied. Exposure to absolute maximum ratings for extended periods may affect device reliability.

Absolute Maximum Ratings are for system-design reference; parameters given are not 100% tested.

#### **OPERATING RANGES**

(T <sub>A</sub> ) 0 to +70°C +4.5 V to +5.5 V
(TA*)55 to +125°C

Operating ranges define those limits between which the functionality of the device is guaranteed.

\*TA is defined as the "instant on" case temperature.

DC CHARACTERISTICS over operating ranges unless otherwise specified (for APL Products, Group A, Subgroups 1, 2, 3 are tested unless otherwise noted)

_	_			Stan	dard	Low Power		Unit	
Parameter Symbol	Parameter Description	Test	Min.	Max.	Min.	Max.			
ЮН	Output HIGH Current	V <sub>OH</sub> = 2.4 V	V <sub>CC</sub> = 4.5 V	-4		-4		mA	
	Output LOW Current	24.7	T <sub>A</sub> = 70°C	8		В		mA	
JOL		V <sub>OL</sub> = 0.4 V	T <sub>A</sub> = 125°C	8		N/A		1 ma	
VIH	Input HIGH Voltage	<u> </u>			6.0	2.0	6.0	٧	
V <sub>IL</sub>	Input LOW Voltage			-0.5	0.8	-0.5	0.8	٧	
lix	Input Load Current	V <sub>SS</sub> ≤ V <sub>I</sub> ≤ V <sub>CC</sub>		-10	10		10	μA	
loz	Output Leakage Current	GND ≤ V <sub>O</sub> ≤ V <sub>CC</sub> Output Disabled	-50	50	-50	50	μΑ		
CI	Input Capacitance	Test Frequency = 1.0		5		5	рF		
C <sub>I/O</sub>	Input/Output Capacitance	T <sub>A</sub> = 25°C, All Pins a (Note 12)			7		7		
loc	V <sub>CC</sub> Operating	Max. V <sub>CC</sub> , CS ≤ V <sub>IL</sub>	T <sub>A</sub> = 0 to+ 70°C		180		125	_ mA	
100	Supply Current	Output Open	T <sub>A</sub> = -55 to+125°C	180	L	N/A			
	Automatic CS Power	Max. V <sub>CC</sub> ,	T <sub>A</sub> = 0 to+70°C		30		20	mA	
ISB	Down Current	(CS ≥ V <sub>IH</sub> )	T <sub>A</sub> = -55 to+125°C		30	N/A			
	Peak Power-On Current	Max. V <sub>CC</sub>	T <sub>A</sub> = 0 to+70°C		50	l	30	Ι.	
IPO		(CS ≥ V <sub>iH</sub> ) (Notes 3 &	T <sub>A</sub> = -55 to+125°C		50		N/A	mA	
laa	Output Short-Circuit	GND ≤ V <sub>O</sub> ≤ V <sub>CC</sub>	TA = 0 to+70°C		±275		±275	mA	
los	Current	(Notes 11, 12)	T <sub>A</sub> = -55 to+125°C	±350			±350		

Notes: 1. Test conditions assume signal transition times of 10 ns or less, timing reference levels of 1.5 V, input pulse levels of 0 to 3.0 V and output loading of the specified IOL/IOH and 30 pF load capa ice. Output timing reference is 1.5 V.

- S LOW and WE LOW. Both signals must be LOW to initiate a 2. The internal write time of the memory is defined by the overlap write and either signal can terminate a write by going HIGH. The data input setup and hold timing should be referenced to the rising edge of the signal that terminates the write.
- 3. A pullup resistor to VCC on the CS input is required to keep the device deselected during VCC power up. Otherwise IpO will exceed values given (Am2148 only).
- 4. The operating ambient temperature is defined as the "instant-ON" case temperature.
- 5. Chip deselected greater than 55 ns prior to selection.
- 6. Chip deselected less than 55 ns prior to selection.
- 7. Transition is measured ±500 mV from steady state voltage with specified loading in Figure B. These parameters are sampled and not 100% tested. 8. WE is HIGH for read cycle.

- 9. Device is continuously selected,  $\overline{\text{CS}} = \text{V}_{\text{IL}}$ .
  10. Address valid prior to or coincident with  $\overline{\text{CS}}$  transition LOW.
- 11. For test purposes, not more than one output at a time should be shorted. Short circuit test duration should not exceed 30
- 12. This parameter is sampled and not 100% tested, but guaranteed by characterization.

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**SWITCHING CHARACTERISTICS** over operating range unless otherwise specified (Note 1) (for APL Products, Group A, Subgroups 9, 10, 11 are tested unless otherwise noted)

	Parameter	Parameter				48/9-45 48/9-45	Am2148/9-55 Am21L48/9-55		Am2148/9-70 Am21L48/9-70			
No.	u Company		Min.	Max.	Min.	Max.	Min.	Max.	Min.	Max.	Unit	
A	lead Cycle				•				<b>_</b>		<del> </del>	
1	tac	Address Valid to Address Do Not Care Time (Read Cycle Time)				45		55		70		ns
2	t <sub>AA</sub>	Address Valid to Data Out Valid Delay (Address Access Time)			35		45	-	55		70	ns
3	<sup>†</sup> ACS1	Chip Select LOW to Data Out	(Note 5)		35		45		55		70	
4	tACS2	Valid (Am2148 only)	(Note 6)		45		55		65		80	ns
5	tacs	Chip Select LOW to Data Out Valid (Am2149 only)			15		20		25		30	ns
6	14.2	Chip Select LOW to	Am2148	10		10		10		10		
		Data Out On (Notes 7 & 12)	Am2149	5		5		5		5		ns
7	t <sub>HZ</sub>	Chip Select HIGH to Data Out Off (Notes 7 & 12)		0	20	0	20	0	20	0	20	ns
8	tон	Output hold after address change		5		5		5		5		ns
9	tPD	Chip Select HIGH to Power Down Delay (Note 12)	Am2148		30		30		30		30	ns
10	tpu	Chip Select LOW to Power Up Delay (Note 12)	Am2148	0		0		0		0		ns
W	rite Cycle											
11	twc	Address Valid to Address Do Not Co Cycle Time)	are (Write	35		45		55	I	70		ns
12	twp	Write Enable LOW to Write Enable HIGH (Note 2)		30		35		40		50		ns
13	twR	Write Enable HIGH to Address		5		5		5		5		ns
14	twz	Write Enable LOW to Output in High Z (Notes 7 & 12)		0	10	0	15	0	20	0	25	ns
15	tow	Data In Valid to Write Enable HIGH		20		20		20		25		ns
16	tDH	Data Hold Time		0		0		0		0		ns
17	t <sub>AS</sub>	Address Valid to Write Enable LOW		0		0		0		0		ns
18	tcw	Chip Select LOW to Write Enable HI (Note 2)	IGH	30		40		50		65		ns
19	tow	Write Enable HIGH to Output in Low (Notes 7 & 12)	0		0		0		0		ns	
20	taw	Address Valid to End of Write		30		40		50	<del>- +</del>	65		ns

Notes: See notes following DC Characteristics table.

#### SWITCHING TEST CIRCUITS



A. Output Load

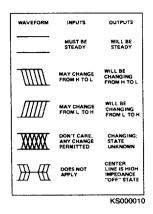
B. Output Load for  $t_{HZ}$ ,  $t_{LZ}$ .  $t_{OW}$ ,  $t_{WZ}$ 

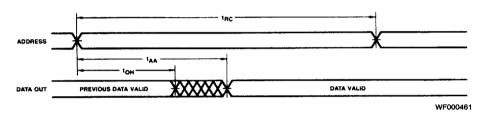
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Am2148/Am2149/Am21L48/Am21L49

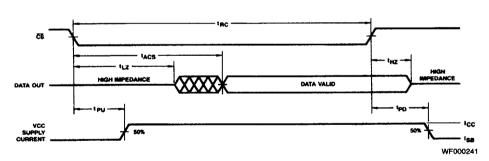
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# SWITCHING WAVEFORMS KEY TO SWITCHING WAVEFORMS





Read Cycle No. 1 (Notes 8, 9)



Read Cycle No. 2 (Notes 8, 10)

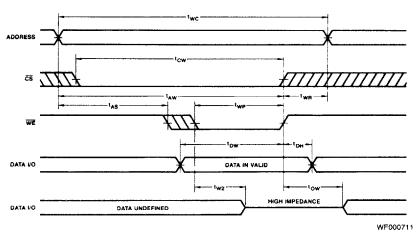
Notes: See notes following DC Characteristics table.

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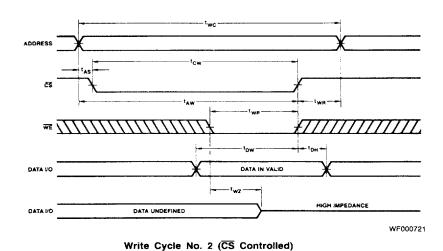
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Am2148/Am2149/Am21L48/Am21L49

#### SWITCHING WAVEFORMS (Cont'd.)



Write Cycle No. 1 (WE Controlled)



Note: If  $\overline{\text{CS}}$  goes HIGH simultaneously with  $\overline{\text{WE}}$  HIGH, the output remains in a high-impedance state.

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#### TYPICAL PERFORMANCE CURVES

